

providing close contact with said contact pads and bonding said heat slug to said substrate panel].

7. (Amended) The semiconductor chip package according to claim 1 [6], [each of said contact bodies being formed near a corner of said top plate, and having a hollow interior and a flat bottom] said semiconductor chip package being a flip chip ball grid array package.

8. 11. (Amended) A semiconductor chip package comprising:

a ball grid array substrate panel having top and bottom surfaces, said bottom surface having a plurality of solder balls attached thereon;

at least one semiconductor chip being mounted substantially in the center of said top surface of said substrate panel;

a supporting structure being bonded on said top surface of said substrate panel, said supporting structure having a central opening for fully exposing a top surface of said semiconductor chip and at least two supporting stubs each being located near a corner of said supporting structure; and

a heat slug having a top plate covering said semiconductor chip and a plurality of flanges extending down to said substrate panel, said top plate being bonded to said semiconductor chip by means of an adhesive material, [and said heat slug being fixed to said substrate panel by means of said supporting structure] said top plate further having at least two contact bodies each having an opening, and said supporting stubs being snapped in the openings of said contact bodies for fixing said heat slug to said substrate panel.

12/ 15. (Amended) The semiconductor chip package according to claim 11, said heat slug  
2 being thermally conductive [supporting structure having a rectangular shape and a  
3 central opening for fully exposing the top surface of said semiconductor chip].

13/ 16. (Amended) The semiconductor chip package according to claim 11 [15], [said  
2 supporting structure further having at least two supporting stubs each being located  
3 near a corner of said supporting structure] said heat slug being thermally conductive.

as 14/ 17. (Amended) The semiconductor chip package according to claim 11 [16], [said top  
2 plate of said heat slug further having at least two contact bodies each having an  
3 opening, and said supporting stubs being snapped in the openings of said contact  
4 bodies for fixing said heat slug to said substrate panel] said semiconductor chip  
5 package being a flip chip ball grid array package.

Claim 18, line 1, change "17" to --11--.

Claim 19, line 1, change "17" to --11--.

#### REMARKS

In the Office Action, Claims 1-2, 5-6, 8, 10-12 and 14 are rejected under 35 USC 102(e) as being anticipated by Barrow and/or Guzik et al. Claims 3-4, 7, 9 and 13 are rejected 35 USC 103(a) as being unpatentable over Barrow and/or Guzik et al. Claims 15-16 are rejected under 35 USC 103(a) as being unpatentable over Barrow and/or Guzik et al. in view of Wang et al. Claims 1-16 are rejected under 35 USC 103(a) as being unpatentable over Wang et al. in view of Barrow. Claims 17-20 would be allowable if rewritten in independent form.

Claims 8-10 are now cancelled. Claim 1 has been amended to distinctly claim the